

Product / Process Change Notification



N° 2019-092-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of an additional wafer production and wafer test location Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia and pad opening for products TLS8x

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **7th July 2020**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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► **Products affected:** Please refer to attached affected product list 1_cip19092_A

► **Detailed Change Information:**

Subject: Introduction of an additional wafer production and wafer test location Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia and pad opening for products TLS8x

Reason: Expansion of wafer production and wafer test to assure continuity of supply and enable flexible manufacturing.

Description:	Old	New
wafer production and wafer test location	<ul style="list-style-type: none">■ Infineon Technologies Austria AG, Villach	<ul style="list-style-type: none">■ Infineon Technologies Austria AG, Villach or■ Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia
pad opening	<ul style="list-style-type: none">■ Pad opening 65 µm	<ul style="list-style-type: none">■ Pad opening 71,6 µm

► **Product Identification:** Wafer lot numbers from Villach start with VExxxxxx
Wafer lot numbers from Kulim with 1Exxxxxx
Traceability assured via date code.
No change in SP ordering number

► **Impact of Change:** Based on the qualification performed, Infineon does not expect any negative impact on quality, function and reliability. No change in fit, form and function expected.
DeQuMa-IDs: SEM-DE-03 / SEM-PW-13 / SEM-TF-01

► **Attachments:** 1_cip19092_A affected product list

► **Time Schedule:**

- Final qualification report: available
- First samples available: on request
- Intended start of delivery: 04-December-2020 or earlier after customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

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Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia and pad opening for products TLS8x



Sales name	SP number	OPN	Package
TLS810C1EJ V33	SP001179582	TLS810C1EJV33XUMA1	PG-DSO-8
TLS810D1EJ V50	SP001179584	TLS810D1EJV50XUMA1	PG-DSO-8